

Notice of References Cited	Application/Control No. 09/940,223		Applicant(s)/Patent Under Reexamination HARKER ET AL.	
	Examiner Allan W Olsen		Art Unit 1763	Page 1 of 1

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*	B	US-6,350,360 B1	02-2002	Bonivert et al.	205/67
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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